## **ON Semiconductor**

#### Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,

ON Semiconductor®



# 4-, 6- and 8-Channel EMI Filter Arrays with ESD Protection

CM1636

#### **Features**

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistorcapacitor (C-R-C) network
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 30dB of attenuation from 800MHz to 3GHz
- UDFN package with 0.40mm lead pitch:
  - •4-ch. = 8-lead UDFN
  - •6-ch. = 12-lead UDFN
  - •8-ch. = 16-lead UDFN
- Tiny UDFN package size:
  - 8-lead: 1.7mm x 1.35mm x 0.50mm
  - 12-lead: 2.5mm x 1.35mm x 0.50mm
  - 16-lead: 3.3mm x 1.35mm x 0.50mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free finishing

## **Applications**

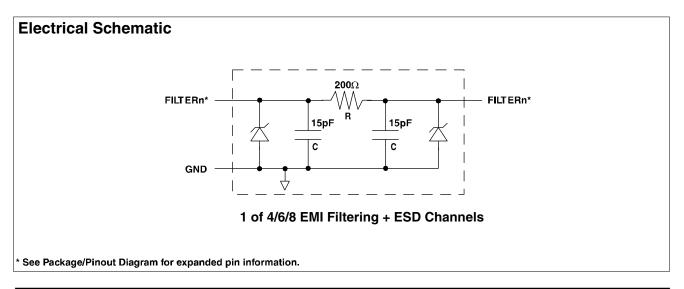
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- EMI filtering for LCD, camera and chip-to-chip data lines

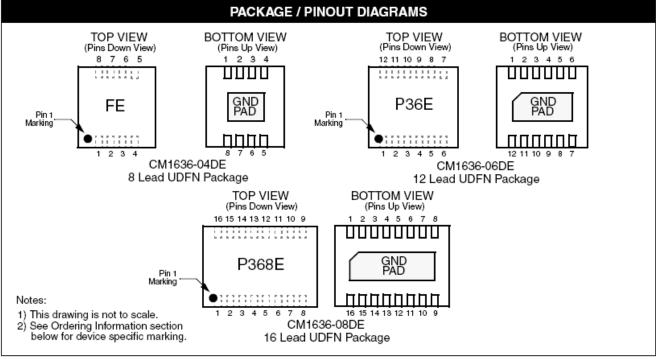
#### **Product Description**

The CM1636 is an EMI filter array with ESD protection, which integrates either four, six or eight pi filters (C-R-C). Each CM1636 filter has component values of 15pF-200W-15pF. These parts include ESD protection diodes on every pin, providing a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of  $\pm 15 \mathrm{kV}$  contact discharge, twice the specification requirement of the IEC 61000-4-2, Level 4 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than  $\pm 30 \mathrm{kV}$ .

This device is particularly well-suited for portable electronics (e.g. mobile handsets, PDAs, notebook computers) because of its small package and easy-to-use pin assignments. In particular, the CM1636 is ideal for EMI filtering and protecting data lines from ESD in wireless handsets.

The CM1636 is available in space-saving, ultra-low-profile, 8-lead, 12-lead and 16-lead 0.4mm pitch UDFN packages. It is fabricated with California Micro Devices'  $Centurion^{TM}$  process and available with lead-free finishing.





	PIN DESCRIPTIONS									
	Pins					Pins				
1636- 04Dx	1636- 06Dx	1636- 08Dx	NAME	DESCRIPTION	1636- 04Dx	1636- 06Dx	1636- 08Dx	NAME	DESCRIPTION	
1	1	1	FILTER1	Filter Channel 1	8	12	16	FILTER1	Filter Channel 1	
2	2	2	FILTER2	Filter Channel 2	7	11	15	FILTER2	Filter Channel 2	
3	3	3	FILTER3	Filter Channel 3	6	10	14	FILTER3	Filter Channel 3	
4	4	4	FILTER4	Filter Channel 4	5	9	13	FILTER4	Filter Channel 4	
	5	5	FILTER5	Filter Channel 5		8	12	FILTER5	Filter Channel 5	
	6	6	FILTER6	Filter Channel 6		7	11	FILTER6	Filter Channel 6	
		7	FILTER7	Filter Channel 7			10	FILTER7	Filter Channel 7	
		8	FILTER8	Filter Channel 8			9	FILTER8	Filter Channel 8	
	GND Pad		GND	Device Ground						

# **Ordering Information**

PART NUMBERING INFORMATION						
		Lead-free Finish				
Leads/Pins	Package	Ordering Part Number <sup>1</sup>	Part Marking			
8	UDFN-08	CM1636-04DE	FE			
12	UDFN-12	CM1636-06DE	P36E			
16	UDFN-16	CM1636-08DE	P368E			

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

CM1636

# **Specifications**

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	RATING	UNITS				
Storage Temperature Range	-65 to +150	°C				
DC Power per Resistor	100	mW				
Package DC Power Rating	300	mW				

STANDARD OPERATING CONDITIONS						
PARAMETER	RATING	UNITS				
Operating Temperature Range	-40 to +85	°C				

#### ELECTRICAL OPERATING CHARACTERISTICS (SEE NOTE 1) SYMBOL UNITS **PARAMETER CONDITIONS** MIN **TYP** MAX R Resistance 160 200 240 Ω **Total Channel Capacitance** At 2.5VDC Reverse Bias, 1MHz, 24 30 36 рF $C_{\text{TOTAL}}$ 30mVAC С Capacitance At 2.5V DC, 1MHz, 30mV AC 15 pF Diode Standoff Voltage 6.0 ٧ $V_{\text{DIODE}}$ $I_{\text{DIODE}} = 10 \mu A$ 1 Diode Leakage Current (reverse $V_{\text{DIODE}} = 3.3V$ 0.1 μΑ LEAK bias) $V_{\text{SIG}}$ Signal Voltage Positive Clamp $I_{LOAD} = 10mA$ 5.6 6.8 ٧ $I_{\scriptscriptstyle LOAD} = -10 mA$ ٧ -0.4 -0.8 **Negative Clamp** $V_{\text{ESD}}$ In-system ESD Withstand Voltage Notes 2 a) Human Body Model, MIL-STDkV +30883, Method 3015 b) Contact Discharge per IEC kV ±15 61000-4-2 Level 4 **Cut-off Frequency** $R = 200\Omega$ , C = 15pF; $f_{c}$ 100 MHz $Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega$ Note 3 Absolute Attenuation @ 1GHz from $Z_{\text{SOURCE}} = 50\Omega$ , $Z_{\text{LOAD}} = 50\Omega$ , 35 dB ${\pmb A}_{\rm 1GHz}$ 0dB Level DC Bias = 0V; Notes 1 and 3 Absolute Attenuation @ 800MHz to $Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega,$ 30 dB A<sub>800MHz - 6GHz</sub> 6GHz from 0dB Level DC Bias = 0V; Notes 1 and 35

Note 1: T<sub>a</sub>=25°C unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Note 3: Attenuation / RF curves characterized by a network analyzer using microprobes.

#### **Performance Information**

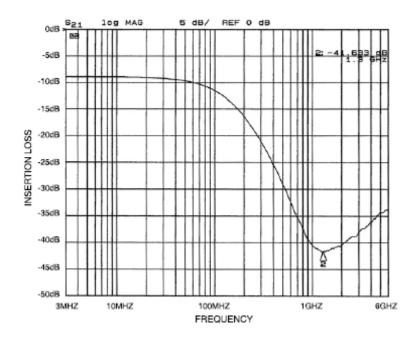


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1636-04DE)

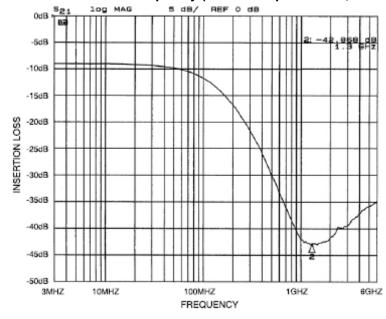


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1636-04DE)

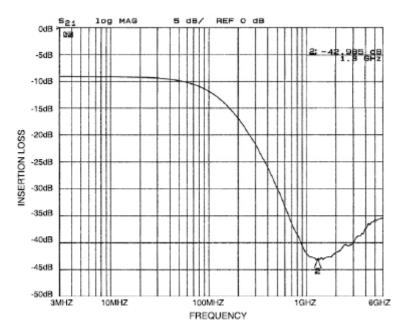


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1636-04DE)

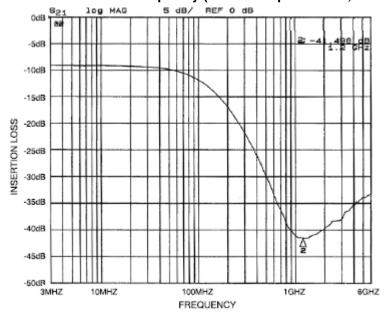


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1636-04DE)

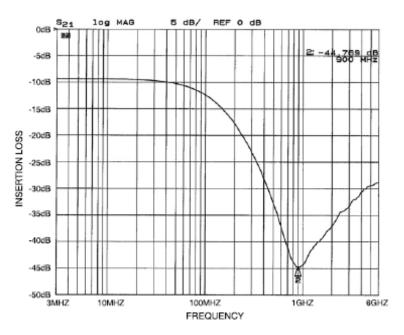


Figure 5. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1636-06DE)

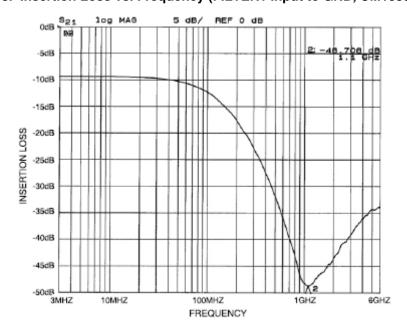


Figure 6. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1636-06DE)

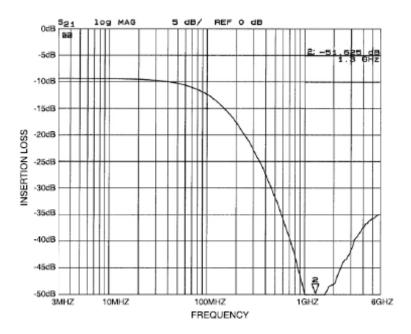


Figure 7. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1636-06DE)

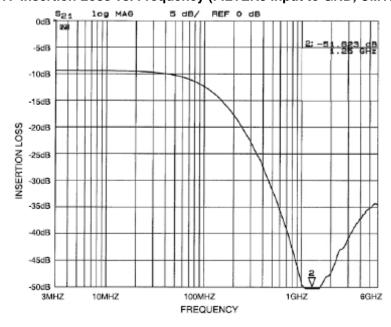


Figure 8. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1636-06DE)

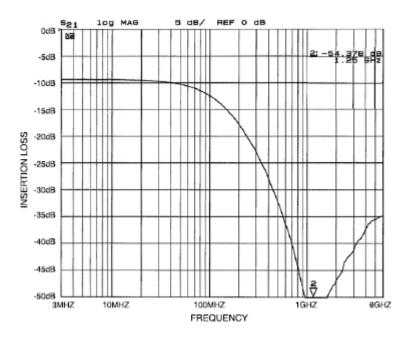


Figure 9. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1636-06DE)

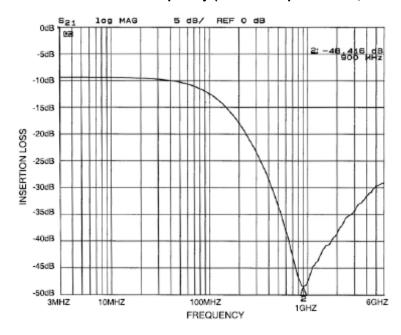


Figure 10. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1636-06DE)

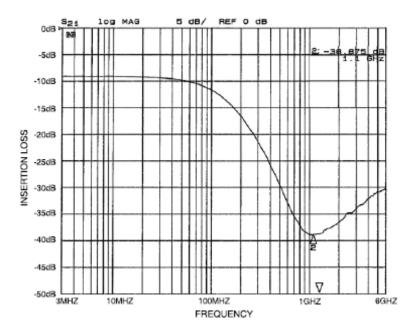


Figure 11. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1636-08DE)

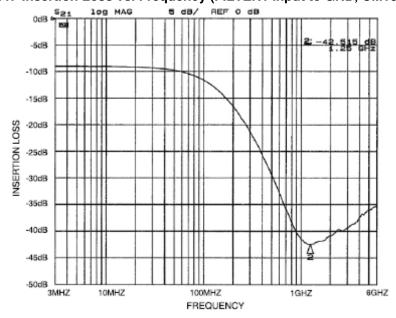


Figure 12. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1636-08DE)

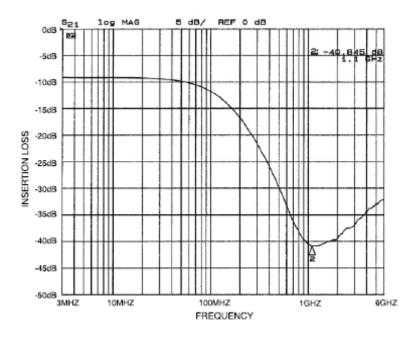


Figure 13. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1636-08DE)

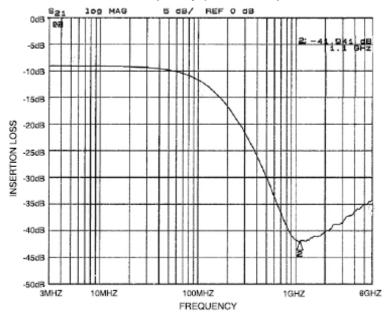


Figure 14. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1636-08DE)

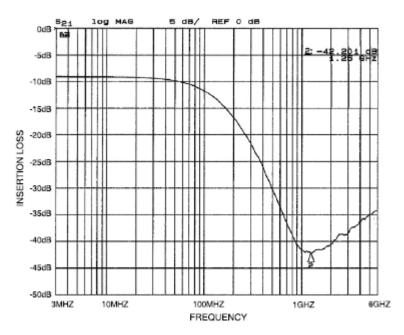


Figure 15. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1636-08DE)

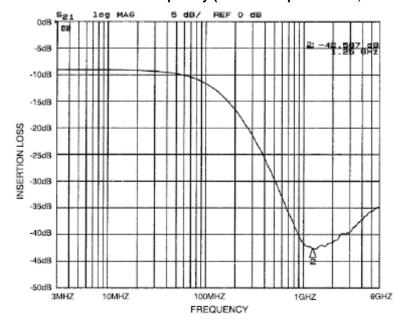


Figure 16. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1636-08DE)

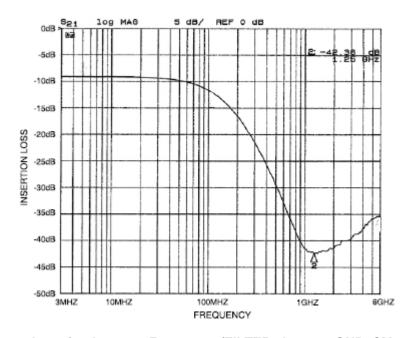


Figure 17. Insertion Loss vs. Frequency (FILTER7 Input to GND, CM1636-08DE)

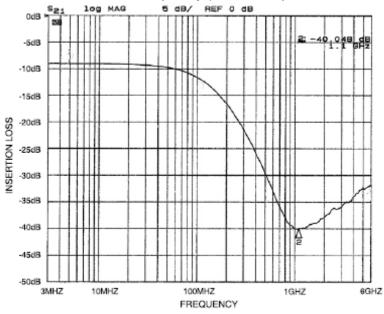


Figure 18. Insertion Loss vs. Frequency (FILTER8 Input to GND, CM1636-08DE)

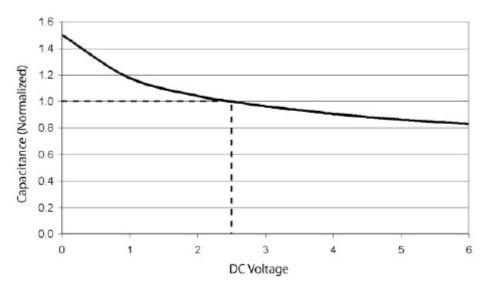


Figure 19. Filter Capacitance vs. Input Voltage over Temperature (normalized to capacitance at 2.5VDC and 25°C)

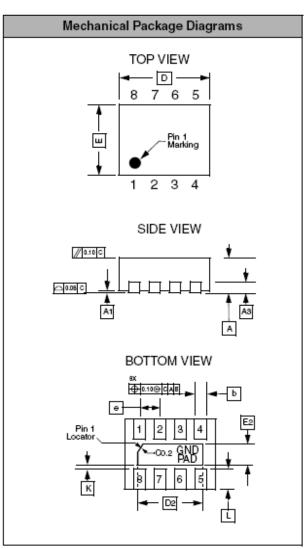
#### **Mechanical Details**

#### **UDFN-08 Mechanical Specifications**

Dimensions for the CM1636 supplied in a 8-lead, 0.4mm pitch UDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS			
Package		uDFN						
JEDEC No.			MO-2	229C*				
Leads				8				
Dim.	IV	lillimete	rs		Inches			
Dilli.	Min	Nom	Max	Min	Nom	Max		
Α	0.45	0.50	0.55	0.018	0.020	0.022		
A1	0.00	0.02	0.05	0.000	0.001	0.002		
А3	C	).127 RE	F	0	0.005 REF			
b	0.15	0.20	0.25	0.006	0.008	0.010		
D	1.60	1.70	1.80	0.063	0.067	0.071		
D2	1.10	1.20	1.30	0.043	0.047	0.051		
E	1.25	1.35	1.45	0.049	0.053	0.057		
E2	0.30	0.40	0.50	0.012	0.016	0.020		
е	(	0.40 BS	С	0	.016 BS	С		
К	(	0.22 RE	F	O	.009 RE	:F		
L	0.15	0.25	0.35	0.006	0.010	0.014		
# per tape and reel			3000	0 pieces				
	Contro	olling din	nension:	millimet	ters			

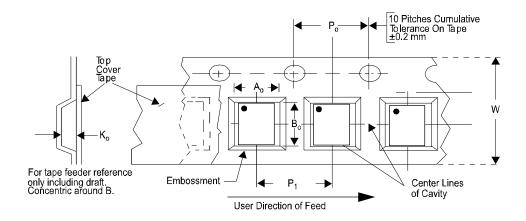
<sup>\*</sup>This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 8-Lead, 0.4mm pitch uDFN package

#### **Tape and Reel Specifications**

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B <sub>o</sub> X A <sub>o</sub> X K <sub>o</sub>	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P <sub>o</sub>	P <sub>1</sub>
CM1636-04DE	1.70 X 1.35 X 0.50	1.95 X 1.60 X 0.60	8mm	178mm (7")	3000	4mm	4mm



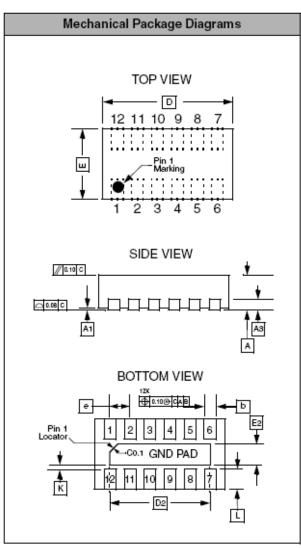
## **Mechanical Details (cont'd)**

#### **UDFN-12 Mechanical Specifications**

Dimensions for the CM1636 suplied in a 12-lead, 0.4mm pitch UDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS			
Package		uDFN						
JEDEC No.			MO-2	229C*				
Leads			1	12				
Dim	IV	lillimete	rs		Inches			
Dim.	Min	Nom	Max	Min	Nom	Max		
Α	0.45	0.50	0.55	0.018	0.020	0.022		
A1	0.00	0.02	0.05	0.000	0.001	0.002		
А3	C	).127 RE	F	0	0.005 REF			
b	0.15	0.20	0.25	0.006	0.008	0.010		
D	2.40	2.50	2.60	0.094	0.098	0.102		
D2	1.90	2.00	2.10	0.075	0.079	0.083		
E	1.25	1.35	1.45	0.049	0.053	0.057		
E2	0.30	0.40	0.50	0.012	0.016	0.020		
е		0.40 BS	С	0	.016 BS	C		
К		0.22 RE	F	0	.009 RE	F		
L	0.15	0.25	0.35	0.006	0.010	0.014		
# per tape and reel			3000	pieces				
	Contro	olling din	nension:	millimet	ers			

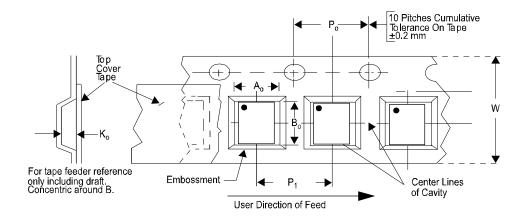
<sup>\*</sup>This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 12-Lead, 0.4mm pitch uDFN package

#### **Tape and Reel Specifications**

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B <sub>o</sub> X A <sub>o</sub> X K <sub>o</sub>	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P <sub>o</sub>	P,
CM1636-06DE	2.50 X 1.35 X 0.50	2.75 X 1.60 X 0.60	8mm	178mm (7")	3000	4mm	4mm



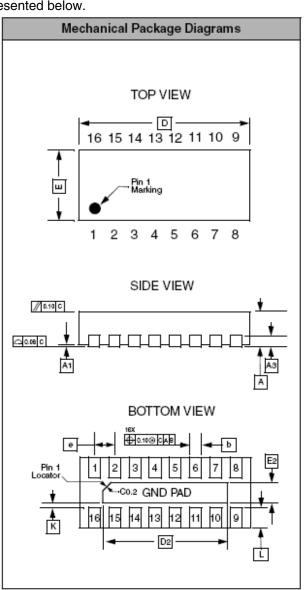
## **Mechanical Details (cont'd)**

#### **UDFN-16 Mechanical Specifications**

Dimensions for the CM1636 suplied in a 16-lead, 0.4mm pitch UDFN package are presented below. The 16-lead, 0.4mm pitch uDFN package dimensions are presented below.

	PAC	KAGE	DIME	NSIO	NS			
Package		uDFN						
JEDEC No.			MO-2	229C*				
Leads			1	16				
Dim.	M	lillimete	rs		Inches			
Dim.	Min	Nom	Max	Min	Nom	Max		
A	0.45	0.50	0.55	0.018	0.020	0.022		
A1	0.00	0.02	0.05	0.000	0.001	0.002		
А3	0	).127 RE	F	C	0.005 REF			
b	0.15	0.20	0.25	0.006	0.008	0.010		
D	3.20	3.30	3.40	0.126	0.130	0.134		
D2	2.70	2.80	2.90	0.106	0.110	0.114		
E	1.25	1.35	1.45	0.049	0.053	0.057		
E2	0.30	0.40	0.50	0.012	0.016	0.020		
е	(	0.40 BS	С	O	.016 BS	SC		
К	(	0.22 RE	F	C	.009 RE	F		
L	0.15	0.25	0.35	0.006	0.010	0.014		
# per tape and reel	3000 pieces							
	Contro	olling din	nension:	millime	ters			

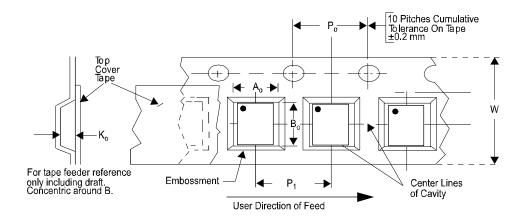
<sup>\*</sup>This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 16-Lead, 0.4mm pitch uDFN package

#### **Tape and Reel Specifications**

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B <sub>o</sub> X A <sub>o</sub> X K <sub>o</sub>	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P <sub>o</sub>	P,
CM1636-08DE	3.30 X 1.35 X 0.50	3.50 X 1.55 X 0.70	12mm	178mm (7")	3000	4mm	4mm



ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### PUBLICATION ORDERING INFORMATION

#### LI TERATURE FULFI LLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, M ddle East and Africa Technical Support:

Phone: 421 33 790 2910

Japan Cust orrer Focus Cent er
Phone: 81-3-5773-3850

ON Semi conduct or Website: www.onsemi.com

Or der Li t er at ur e: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative